

04-25-2002



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To the Honorable Commissioner of Patents and Trademarks

inal documents or copy thereof.

<p>1. Name of conveying party(ies): Patrick Kevin Egan</p> <p>Additional names of conveying party(ies) attached? <input type="checkbox"/> yes <input checked="" type="checkbox"/> no</p> <p>3. Nature of Conveyance <input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other _____</p> <p>Execution Date: April 15, 2002</p>		<p>2. Name and address of receiving party(ies): Name: <u>International Business Machines Corporation</u> Internal Address: _____ _____ _____ Street Address: <u>New Orchard Road</u> City <u>Armonk</u> State <u>New York</u> Zip <u>10504</u> Additional name(s) & address(es) attached? <input type="checkbox"/> yes <input checked="" type="checkbox"/> no</p>	
<p>4. Application number(s) or patent number(s): TITLE: <u>SEQUENCING CIRCUIT FOR APPLYING A HIGHEST VOLTAGE SOURCE TO A CHIP</u> If this document is being filed together with a new application, the execution date of the application is <u>April 15, 2002</u>.</p> <p>A. Patent Application No(s). Docket ROC920010377US1</p> <p>B. Patent No(s). <u>10/122994</u></p> <p>Additional numbers attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>			
<p>5. Name and address of party to whom correspondence concerning document should be mailed: Leslie J. Payne IBM Corporation - Dept. 917 3605 Highway 52 North Rochester, MN 55901</p>		<p>6. Total number of applications and patents involved: <u>1</u></p> <p>7. Total fee (37 CVF 3.41): <u>\$ 40.00</u> <input type="checkbox"/> Enclosed <input checked="" type="checkbox"/> Authorized to be charged to deposit account <input checked="" type="checkbox"/> Total fee due <input checked="" type="checkbox"/> Any deficiencies in the enclosed fees</p> <p>8. Deposit account number: <u>09-0465</u> (Attach duplicate copy of this page if paying by deposit account)</p>	
<p>04/24/2002 DBYRNE 00000227 090465 10122994 01 FC:581</p>		<p>40.00 CH</p>	
<p>DO NOT USE THIS SPACE</p>			
<p>9. Statement and signature To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.</p> <p><u>Leslie J. Payne, Reg. No. 26,378</u> Name of Person Signing</p> <p><u>[Signature]</u> Signature</p> <p><u>April 15, 2002</u> Date</p> <p>Total number of pages comprising cover sheet: <u>1</u></p>			

10/122994
U.S. PTO



ASSIGNMENT

Whereas, I

(1) Patrick Kevin Egan
County of OlmstedCity of Rochester,
and State of Minnesota,

have invented certain improvements in

SEQUENCING CIRCUIT FOR APPLYING A HIGHEST VOLTAGE SOURCE TO A CHIP

and have executed, respectively, a United States patent application therefor on

Dates

Inventor Signed

Declaration (1) April 15, 2002

And whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I the above named hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to IBM, its successors and assigns; and I hereby agree that IBM may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

Signed

Inventor at Rochester, MN
(1)
on 04/15/2002.



(Patrick Kevin Egan) Inventor
First Name Initial Last Name Signature